HM514900, HM514900L Series ——— Preliminary

524,288-word × 9-bit Dynamic Random Access Memory

HITACHI/ LOGIC/ARRAYS/MEM

The Hitachi HM514900 are CMOS dynamic RAM organized as 524,288-word × 9-bit. HM514900 have realized higher density, higher performance and various functions by employing 0.8 µm CMOS process technology and some new CMOS circuit design technologies. The HM514900 offer Fast Page Mode as a high speed access mode.

Multiplexed address input permits the HM514900 to be packaged in standard 400-mil 28-pin plastic SOJ, standard 400-mil 28-pin plastic ZIP and 400mil 28-pin plastic TSOP.

Features

Single 5 V (± 10%)

High speed

- Access time: 70 ns/80 ns/100 ns (max)

· Low power dissipation

- Active mode: 605 mW/550 mW/495 mW

(max)

- Standby mode: 11 mW (max)

1.1 mW (max) (L-version)

· Fast page mode capability

· 1,024 refresh cycles: 16 ms 128 ms (L-version)

· 3 variations of refresh

- RAS-only refresh

- CAS-before-RAS refresh

- Hidden refresh

· Battery back up operation (L-version)

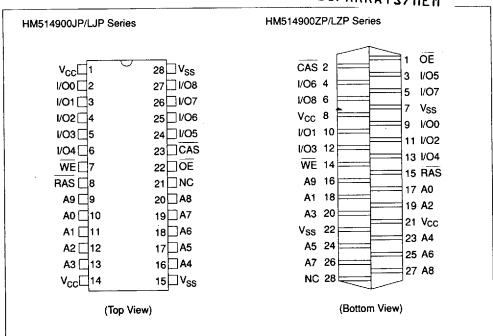
Ordering Information

Type No.	Access time	Package
HM514900JP-7	70 ns	400-mil 28-pin
HM514900JP-8	80 ns	plastic SOJ
HM514900JP-10	100 ns	(CP-28DA)
HM514900ZP-7	70 ns	400-mil 28-pin
HM514900ZP-8	80 ns	plastic ZIP
HM514900ZP-10	100 ns	(ZP-28)
HM514900TT-7	70 ns	400-mil 28-pin
HM514900TT-8	80 ns	plastic TSOP
HM514900TT-10	100 ns	(TTP-28DA)
HM514900LJP-7	70 ns	400-mil 28-pin
HM514900LJP-8	80 ns	plastic SOJ
HM514900LJP-10	100 ns	(CP-28DA)
HM514900LZP-7	70 ns	400-mil 28-pin
HM514900LZP-8	80 ns	plastic ZIP
HM514900LZP-10	100 ns	(ZP-28)
HM514900LTT-7	70 ns	400-mil 28-pin
HM514900LTT-8	80 ns	plastic TSOP
HM514900LTT-10	100 ns	(TTP-28DA)

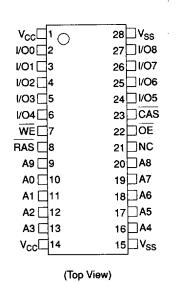
This document contains information on a new product. Specification and information contained herein are subject to change without notice.

Pin Arrangement

HITACHI/ LOGIC/ARRAYS/MEM



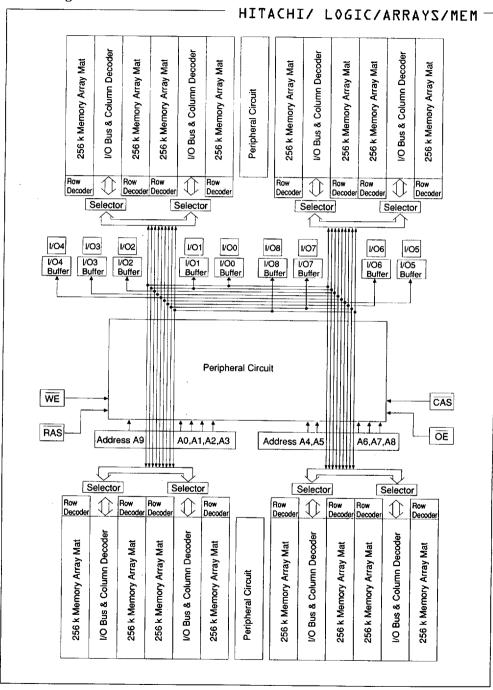




Pin Description

Pin name	Function	
A0 - A9	Address input Row address	A0 - A9
- -	Column address Refresh address	A0 - A8 A0 - A9
1/00 – 1/08	Data-in/data-out	
RAS	Row address strob	98
CAS	Column address s	trobe
WE	Read/write enable	
OE	Output enable	
v _{cc}	Power (+5 V)	
V _{SS}	Ground	

Block Diagram



		_
	HITACHI/ LOGIC	/ARRAYS/MEI
Symbol	Value	Unit
V _T	-1.0 to +7.0	٧
Vcc	-1.0 to +7.0	V
lout	50	mA
PŢ	1.0	w
Topr	0 to +70	°C
Tstg	-55 to +125	°C
	V _T V _{CC} lout P _T Topr	Symbol Value V _T -1.0 to +7.0 V _{CC} -1.0 to +7.0 lout 50 P _T 1.0 Topr 0 to +70

Recommended DC Operating Conditions (Ta = 0 to +70°C) *2

Parameter		Symbol	Min	Тур	Max	Unit	Note
Supply voltage		V _{SS}	V _{SS} 0		0	٧	
		v _{cc}	4.5	5.0	5.5	٧	1
Input high vol	Itage	V _{iH}	2.4		6.5	٧	1
Input low voltage	(I/O pin)	V _{IL}	-1.0	_	8.0	٧	1
	(Others)	VIL	-2.0	_	8.0	٧	1 .

 $[\]begin{array}{lll} \mbox{Notes:} & \mbox{1.} & \mbox{All voltage referenced to V_{SS}.} \\ 2. & \mbox{The supply voltage with all V_{CC} pins must be on the same level.} \\ & \mbox{The supply voltage with all V_{SS} pins must be on the same level.} \\ \end{array}$

HITACHI/ LOGIC/ARRAYS/MEM

DC Characteristics (Ta = 0 to +70°C, $V_{CC} = 5 \text{ V} \pm 10\%$, $V_{SS} = 0 \text{ V}$) *5

HM514900-7	HM514900-8	HM514900-10
------------	------------	-------------

		1 11110	17000 1	IIII	17000-0	111110	14300-1	U		
Parameter	Symbol	Min	Max	Min	Max	Min	Max	- Unit	Test conditions	Notes
Operating current	lcc ₁	_	110	_	100	_	90	mA	RAS, CAS cycling t _{RC} = min	1, 2
Standby current	lcc2	_	2	_	2	_	2	mA	TTL interface RAS, CAS = V _{IH} Dout = High-Z	
	_	_	1	_	1	_	1	mA	CMOS interface RAS, CAS ≥ V _{CC} – 0.2 V Dout = High-Z	
Standby current (L-version)		_	200	_	200	_	200	μА	CMOS interface RAS, CAS ≥ V _{CC} - 0.2 V Dout = High-Z	
RAS-only refresh current	Іссз	_	110	_	100	_	90	mA	t _{RC} = min	2
Standby current	lcc5	_	5	_	5		5	mA	RAS = V _{IH} CAS = V _{IL} Dout = enable	1
CAS-before-RAS refresh current	I _{CC6}		110		100	-	90	mA	t _{RC} = min	
Fast page mode current	I _{CC7}	_	110	_	100	_	90	mA	t _{PC} = min	1, 3
Battery back up current (Standby with CBR refresh) (L-version only)	I _{CC10}		300	_	300		300	μА	Standby: CMOS interface Dout = High-Z CBR refresh: t_{RC} = 125 μ s $t_{RAS} \le 1 \mu$ s, CAS = V_{IL} WE = V_{IH}	4
Input leakage current	lu	-10	10	-10	10	-10	10	μА	0 V ≤ Vin ≤ 7 V	
Output leakage current	lLO	-10	10	-10	10	-10	10	μА	0 V ≤ Vout ≤ 7 V Dout = disable	
Output high voltage	V _{OH}	2.4	v _{cc}	2.4	v _{cc}	2.4	V _{CC}	٧	High lout = -5 mA	
Output low voltage	V _{OL}	0	0.4	0	0.4	0	0.4	٧	Low lout = 4.2 mA	

- Notes: 1. I_{CC} depends on output load condition when the device is selected I_{CC} max is specified at the output open condition.

Address can be changed once or less while RAS = V_{IL}.
 Address can be changed once or less while CAS = V_{IH}.
 V_{IH} ≥ V_{CC} – 0.2 V, V_{IL} ≤ 0.2 V
 The supply voltage with all V_{CC} pins must be on the same level. The supply voltage with all V_{SS} pins must be on the same level.

Capacitance (Ta = 25°C, V_{CC} = 5 V ± 10%)

Parameter	Symbol	Тур	Max	Unit	Notes
Input capacitance (Address)	C _{I1}	_	5	pF	1
Input capacitance (Clocks)	C _{I2}		7	рF	1
Output capacitance (Data-in, Data-out)	C _{I/O}	_	10	pF	1, 2

Notes: 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.

2. $\overline{CAS} = V_{IH}$ to disable Dout.

HITACHI/ LOGIC/ARRAYS/MEM

AC Characteristics (Ta = 0 to 70°C, $V_{CC} = 5 \text{ V} \pm 10\%$, $V_{SS} = 0 \text{ V}$) *1, *14, *15

Test condisions

• Input rise and fall times: 5 ns

Input rise and fall times: 5 ns
Input timing reference levels: 0.8 V, 2.4 V

 Output load: 2 TTL gate + C_L (100 pF) (Including scope and jig)

Read, Write, Read-Modify-Write and Refresh Cycles (Common Parameters)

								_	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Random read or write cycle time	^t RC	130	_	150	_	180	_	ns	
RAS precharge time	t _{RP}	50	_	60	_	70	_	ns	
RAS pulse width	tRAS	70	10000	80	10000	100	10000	ns	
CAS pulse width	t _{CAS}	20	10000	20	10000	25	10000	ns	
Row address setup time	^t ASR	0	_	0		0	_	ns	
Row address hold time	^t RAH	10	_	10	_	15	_	ns	
Column address setup time	t _{ASC}	0	_	0	_	0	_	ns	
Column address hold time	^t CAH	15	-	15	_	20	_	ns	-
RAS to CAS delay time	t _{RCD}	20	50	20	60	25	75	ns	8
RAS to column address delay time	t _{RAD}	15	35	15	40	20	55	ns	9
RAS hold time	^t RSH	20	_	20	_	25		ns	
CAS hold time	^t csH	70	_	80		100	_	ns	
CAS to RAS precharge time	tCRP	15		15	_	15	_	ns	

61E D 🖿 4496203 0023051 521 **=**HIT2

- HITACHI/ LOGIC/ARRAYS/MEM

HM514900, HM514900L Series

Read, Write, Read-Modify-Write and Refresh Cycles (Common Parameters) (cont)

HM514900-7 HM514900-8 HM514900-10

Parameter	Symbol	Min	Max	Min	Max	Min	Max	_ Unit	Note
OE to Din delay time	t _{ODD}	20	_	20		25	_	ns	
OE delay time from Din	t _{DZO}	0	_	0	_	0	_	ns	
CAS setup time from Din	t _{DZC}	0	_	0	_	0		ns	
Transition time (rise and fall)	t _T	3	50	3	50	3	50	ns	7
Refresh period	^t REF	_	16		16		16	ms	
Refresh period (L-version)	t _{REF}	_	128		128	_	128	ms	

Read Cycle

Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes	
Access time from RAS	^t RAC		70	_	80	_	100	ns	2, 3	
Access time from CAS	tCAC		20	_	20	_	25	ns	3, 4, 13	
Access time from address	t _{AA}	_	35	_	40	_	45	. ns	3, 5, 13	
Access time from OE	^t OAC	_	20	_	20	_	25	ns		
Read command setup time	t _{RCS}	0	_	0		0	_	ns		
Read command hold time to CAS	^t RCH	0	_	0	_	0		ns		
Read command hold time to RAS	t _{RRH}	0	_	0		0	_	ns		
Column address to RAS lead time	tRAL	35	_	40	_	45	_	ns		
Output buffer turn-off time	t _{OFF1}	0	15	0	15	0	20	ns	6	
Output buffer turn-off to OE	t _{OFF2}	0	15	0	15	0	20	ns	6	
CAS to Din delay time	t _{CDD}	15	_	15	_	20	_	ns		

Write Cycle

HITACHI/ LOGIC/ARRAYS/MEM

HM514900-7 HM514900-8 HM514900-10

								_	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Write command setup time	twcs	0	_	0	-	0		ns	10
Write command hold time	twch	15	_	15	_	20	_	ns	
Write command pulse width	t _{WP}	10	_	10	_	20		ns	
Write command to RAS lead time	^t RWL	20	_	20	_	25	_	ns	• • • • • • • • • • • • • • • • • • • •
Write command to CAS lead time	tcwL	20	_	20	_	25		ns	
Data-in setup time	t _{DS}	0	_	0	_	0	_	ns	11
Data-in hold time	t _{DH}	15	_	15		20	_	ns	11
CAS to OE delay time	t _{COD}	_	0	_	0		0	ns	18

Read-Modify-Write Cycle

HM514900-7 HM514900-8 HM514900-10

Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Read-modify-write cycle time	t _{RWC}	180	_	200	_	245	_	ns	
RAS to WE delay time	^t RWD	95	_	105	_	135	_	ns	10
CAS to WE delay time	tcwd	45	_	45	_	60	_	ns	10
Column address to WE delay time	t _{AWD}	60	_	65		80	_	ns	10, 13
OE hold time from WE	^t OEH	20	_	20	_	25	_	ns	

Refresh Cycle

Parameter	Symbol	Min	Max	Min	Max	Min	Max	– Unit	Note
CAS setup time (CAS-before-RAS refresh cycle)	t _{CSR}	10	_	10	_	10		ns	
CAS hold time (CAS-before-RAS refresh cycle)	^t CHR	10	_	10	_	10	_	ns	
RAS precharge to CAS hold time	t _{RPC}	10	_	10	_	10	_	ns	
CAS precharge time in normal mode	^t CPN	10	_	10		10	_	ns	

HITACHI/ LOGIC/ARRAYS/MEM

Fast Page Mode Cycle

HM514900-7 HM514900-8 HM514900-10

Parameter	Symbol								
		Min	Max	Min	Max	Min	Max	 Unit	Notes
Fast page mode cycle time	t _{PC}	50		55	_	60		ns	
Fast page mode CAS precharge time	t _{CP}	15		15		15	_	ns	
Fast page mode RAS pulse width	t _{RASC}	_	100000) —	10000	0 —	100000	ns	12
Access time from CAS precharge	t _{ACP}	_	40	_	45	_	50	ns	3, 13
RAS hold time from CAS precharge	†RHCP	40	_	45	_	50		ns	
Fast page mode read-modify-write cycle CAS precharge to WE delay time	^t CPW	65		70	_	85	_	ns	
Fast page mode read-modify-write cycle time	^t PCM	95	_	100		110		ns	

Counter Test Cycle

Parameter	Symbol	Min	Max	Min	Max	Min	Max	– Unit	Note
CAS precharge time in counter test cycle	^t CPT	50	_	50	_	50		ns	

- Notes: 1. AC measurements assume $t_T = 5$ ns.
 - 2. Assumes that $t_{RCD} \le t_{RCD}$ (max) and $t_{RAD} \le t_{RAD}$ (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, tRAC exceeds the value shown.
 - 3. Measured with a load circuit equivalent to 2 TTL loads and 100 pF.
 - Assumes that t_{RCD} ≥ t_{RCD} (max) and t_{RAD} ≤ t_{RAD} (max).
 - Assumes that t_{RCD} ≤ t_{RCD} (max) and t_{RAD} ≥ t_{RAD} (max).
 - 6. t_{OFF} (max) defines the time at which the output achieves the open circuit condition and is not referenced to output voltage levels.
 - 7. VIH (min) and VIL (max) are reference levels for measuring timing of input signals. Also, transition times are measured between VIH and VIII.
 - 8. Operation with the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only, if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC}.
 - 9. Operation with the t_{RAD} (max) limit insures that t_{RAC} (max) can be met, t_{RAD} (max) is specified as a reference point only, if t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled exclusively by tAA.
 - 10. twcs, trwp, towp and tawp are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only: if twcs ≥ twcs (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{RWD} \ge t_{RWD}$ (min), $t_{CWD} \ge t_{CWD}$ (min), $t_{AWD} \ge t_{AWD}$ (min) and $t_{CPW} \ge t_{CPW}$ (min), the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.

- 11. These parameters are referenced to CAS leading edge in an early write cycle and to WE leading edge in a delayed write or a read-modify-write cycle.
- 12. t_{RASC} defines RAS pulse width in fast page mode cycles.

13. Access time is determined by the longer of tAA or tCAC or tACP.

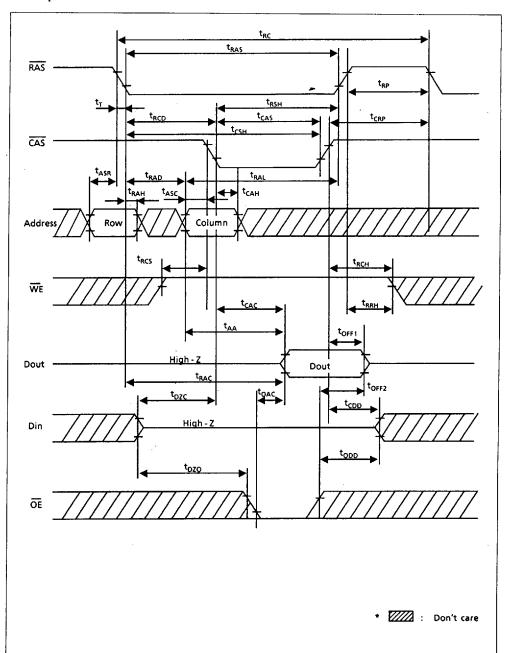
- 14. An initial pause of 100 μs is required after power up followed by a minimum of eight initialization cycles (RAS-only refresh cycle or CAS-before-RAS refresh cycle). If the internal refresh counter is used, a minimum of eight CAS-before-RAS refresh cycles is required.
- In delayed write or read-modify-write cycles, OE must disable output buffer prior to applying data to the device.

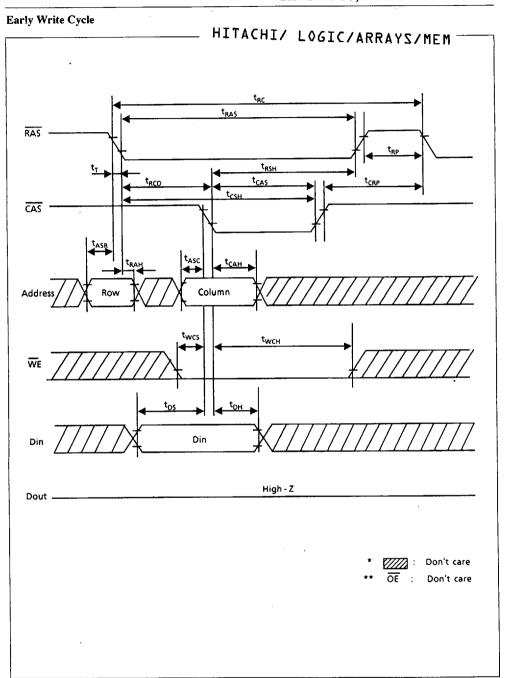
16. Either $t_{\mbox{\scriptsize RCH}}$ or $T_{\mbox{\scriptsize RRH}}$ must be satisfied for a read cycle.

- The supply voltage with all V_{CC} pins must be on the same level.
 The supply voltage with all V_{SS} pins must be on the same level.
- 18. Do not enable Dout buffer when using delayed write timing.

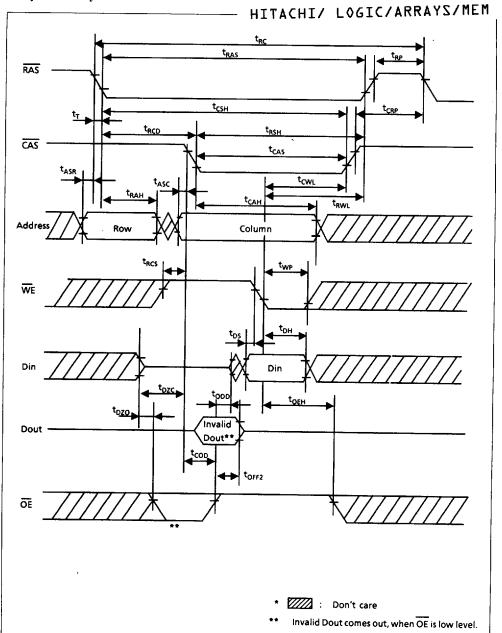
Timing Waveforms

Read Cycle

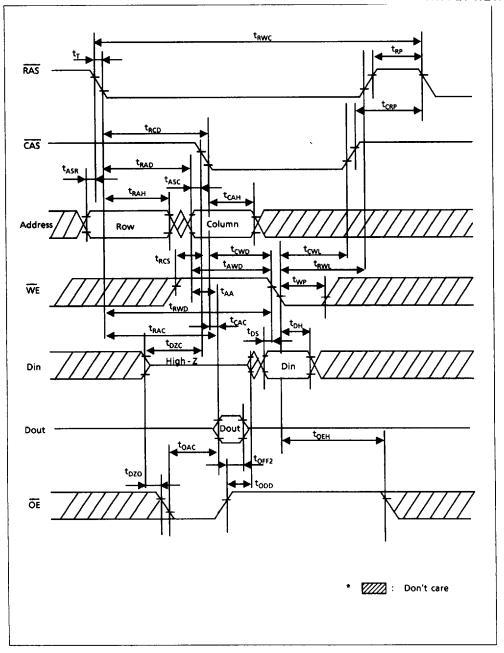




Delayed Write Cycle

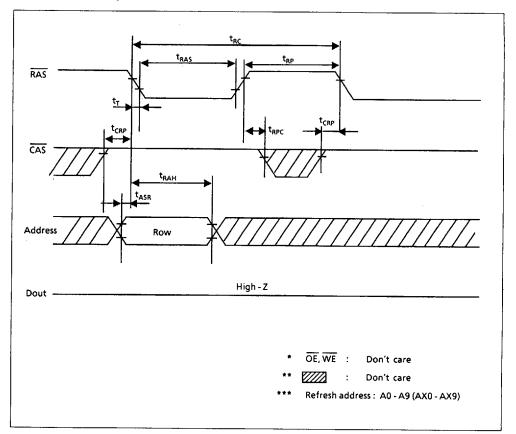


Read-Modify-Write Cycle

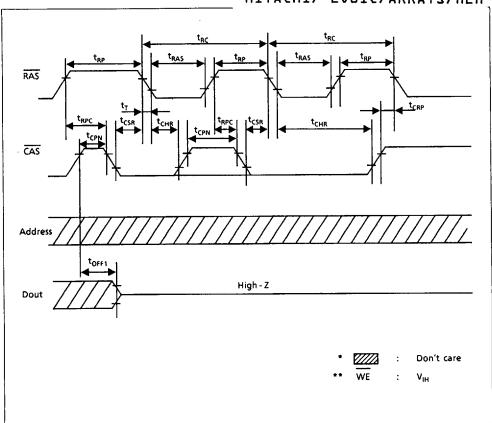


HITACHI/ LOGIC/ARRAYS/MEM

RAS-Only Refresh Cycle

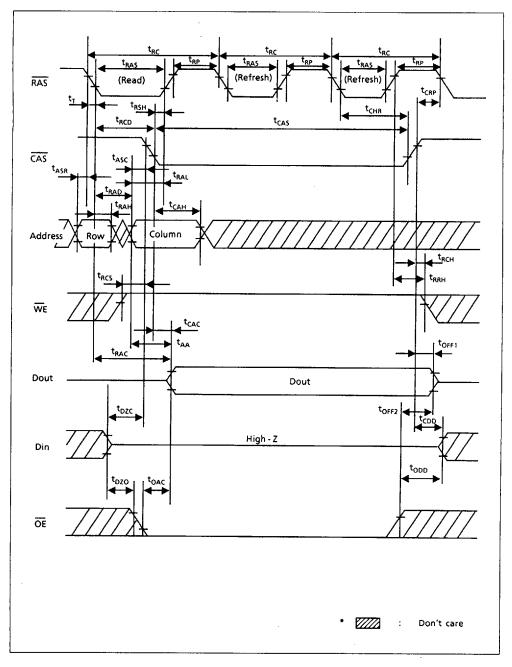


CAS-Before-RAS Refresh Cycle

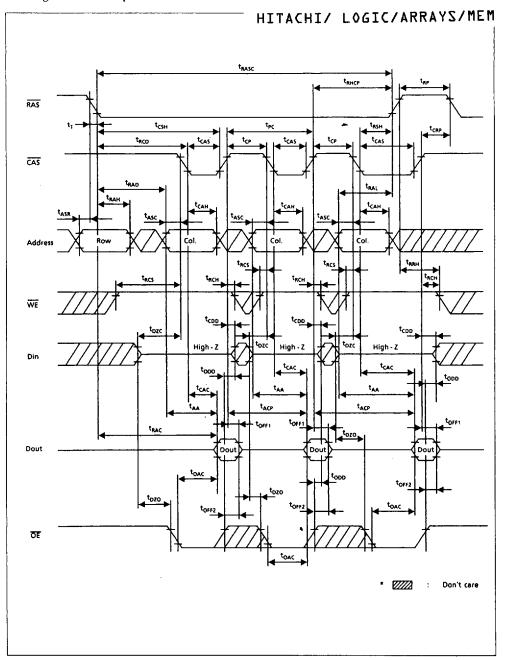


HITACHI/ LOGIC/ARRAYS/MEM -

Hidden Refresh Cycle

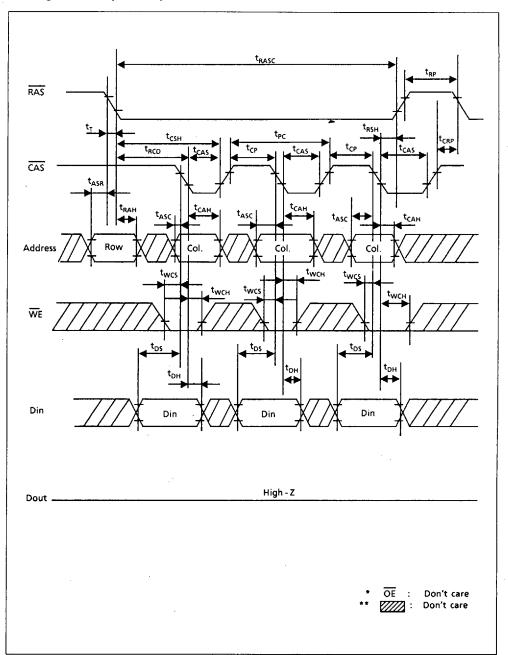


Fast Page Mode Read Cycle

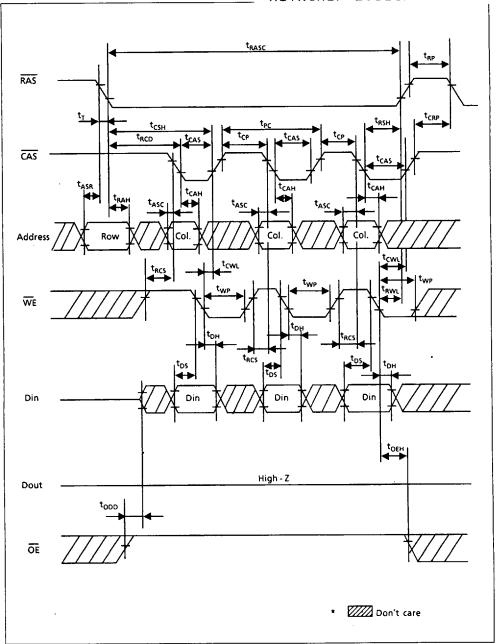


HITACHI/ LOGIC/ARRAYS/MEM

Fast Page Mode Early Write Cycle

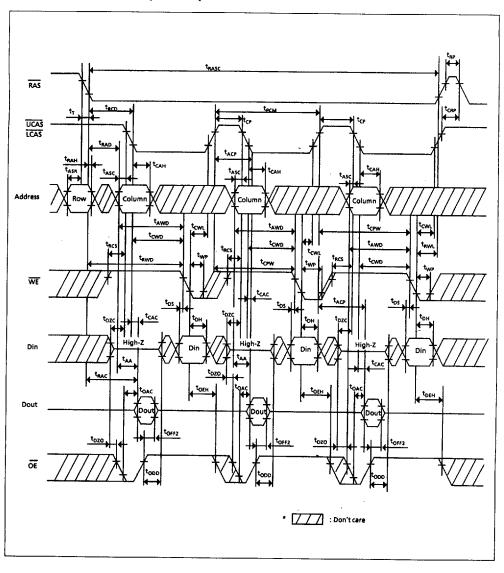


Fast Page Mode Delayed Write Cycle

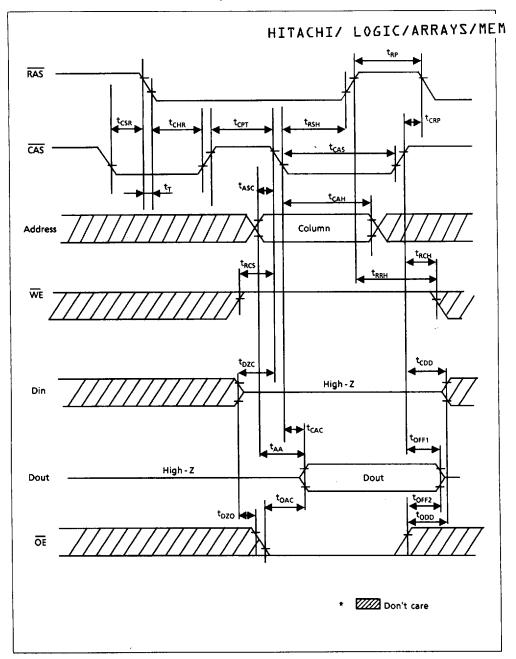


HITACHI/ LOGIC/ARRAYS/MEM

Fast Page Mode Read-Modify-Write Cycle



CAS-Before-RAS Refresh Counter Check Cycle (Read)



CAS-Before-RAS Refresh Counter Check Cycle (Write)

